

Device for automatically brazing hardened tips

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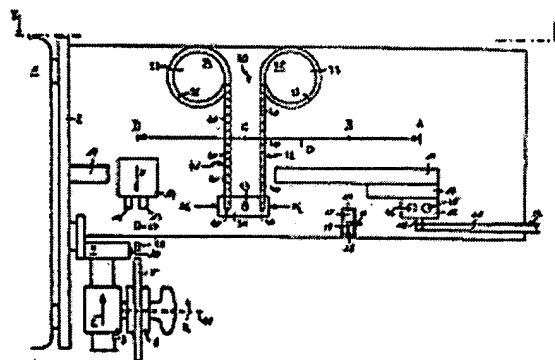
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1. Apparatus for the automatic soldering of hard metal teeth (40) on to the prongs of a circular saw blade (5) with the following features : a) there are provided a tooth transport equipment (16, 17) individually taking over hard metal teeth placed ready in defined position by a tooth feeding equipment (30) and transporting and transforming them to a soldering mount (14), b) a solder platelet deposit equipment (17, 18) laying a respective solder platelet on the upward facing soldering side of each of the hard metal teeth and c) a fluxing agent feeding equipment (24, 27) introducing a fluxing agent (25) between the soldering side of each hard metal tooth and the associated solder platelet, and d) the soldering mount (14) is movable to and fro between a transfer position (D), in which it takes over the hard metal tooth (40) brought forward by the tooth transport equipment (16, 17), and a soldering position, in which the hard metal tooth provided with fluxing agent (25) and a solder platelet (21) is pressable with the solder platelet forward against a prong of the circular saw blade (5) during the heating-up, soldering and cooling-down operations, and characterised by the following features, e) that the tooth transport equipment (16, 17) is movable to and fro between the tooth feeding equipment (30) and the transfer position (D) for each individual hard metal tooth (40), f) that the solder platelet deposit equipment is constructed as solder platelet between a equipment (17, 18), which is movable to and fro for each individual solder platelet between a solder platelet receiving position (A) and a solder platelet deposit position (47) and g) that the solder platelet deposit position (47) is arranged on the movement path of the soldering



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